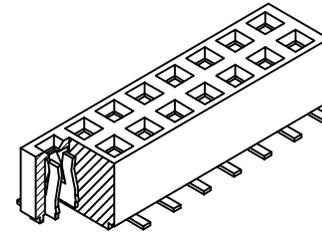
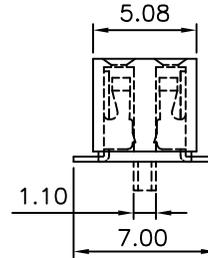
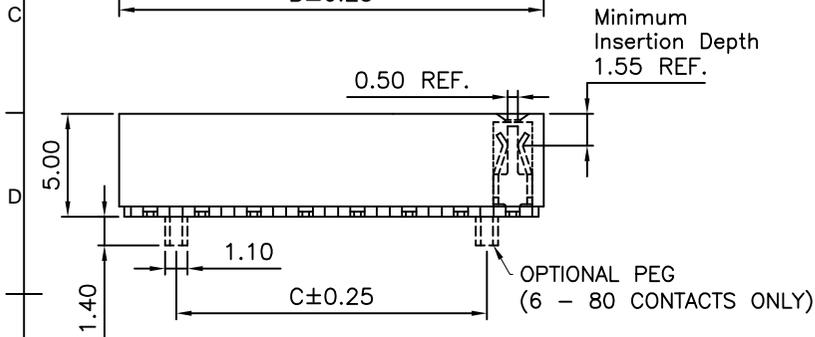


RECOMMENDED PCB LAYOUT

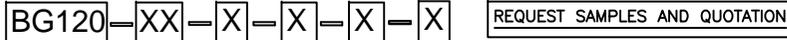


CONTACTS	DIMENSIONS		
	A	B	C
4	2.54	5.58	N/A
6	5.08	8.12	2.54
8	7.62	10.66	5.08
10	10.16	13.20	7.62
12	12.70	15.74	10.16
14	15.24	18.28	12.70
16	17.78	20.82	15.24
18	20.32	23.36	17.78
20	22.86	25.90	20.32
22	25.40	28.44	22.86
24	27.94	30.98	25.40
26	30.48	33.52	27.94
28	33.02	36.06	30.48
30	35.56	38.60	33.02
32	38.10	41.14	35.56
34	40.64	43.68	38.10
36	43.18	46.22	40.64
38	45.72	48.76	43.18
40	48.26	51.30	45.72
42	50.80	53.84	48.26
44	53.34	56.38	50.80
46	55.88	58.92	53.34
48	58.42	61.46	55.88
50	60.96	64.00	58.42
52	63.50	66.54	60.96
54	66.04	69.08	63.50
56	68.58	71.62	66.04
58	71.12	74.16	68.58
60	73.66	76.70	71.12
62	76.20	79.24	73.66
64	78.74	81.78	76.20
66	81.28	84.32	78.74
68	83.82	86.86	81.28
70	86.36	89.40	83.82
72	88.90	91.94	86.36
74	91.44	94.48	88.90
76	93.98	97.02	91.44
78	96.52	99.56	93.98
80	99.06	102.10	96.52

SPECIFICATIONS 规格

CURRENT RATING 电流额定值: 3 AMP
INSULATOR RESISTANCE 绝缘电阻值: 1000 MEGOHMS MIN
CONTACT RESISTANCE 接触电阻值: 20M OHMS MAX
DIELECTRIC WITHSTANDING 耐电压: 600V AC/DC
OPERATING TEMPERATURE 工作温度: -40°C TO +150°C
CONTACT MATERIAL 端子物料: PHOSPHOR BRONZE
INSULATOR MATERIAL 绝缘体物料:
 STANDARD 标准物料: POLYAMIDE 聚酰胺, NYLON 6T, UL 94-V0
 OPTIONS 可选物料: POLYESTER 聚酯, LCP, UL 94-V0
SOLDERING PROCESS 可焊性:
 NYLON 6T (STANDARD 标准物料) -
 IR REFLOW 回流焊: 260°C for 10 sec.
 WAVE 波峰焊: 230°C for 5-10 sec.
 MANUAL SOLDER 人工焊接: 350°C for 3-5 sec
 LCP (OPTION 可选物料) -
 IR REFLOW 回流焊: 260°C for 10 sec.
 WAVE 波峰焊: 250°C for 5-10 sec.
 MANUAL SOLDER 人工焊接: 350°C for 3-5 sec
MATES WITH 配套之母座 (SUBJECT TO PIN LENGTH 在端子长度适合的条件下):
 BG025 BG040 BG045 BG050 BG065
 BG070 BG085

Ordering Grid



- No. of Contacts: 04 to 80
- Contact Plating: A = Gold Flash, B = Selective Gold Flash, C = Tin
- Insulator Material: N = Nylon 6T (Standard), L = LCP
- Locating Peg: 0 = No Peg, 1 = With Peg (6 - 80 Pins Only)
- Packing Options: C = Tape and Reel with Film (Standard), B = Tape and Reel with Cap, D = Tube, E = Tube with Cap, F = Tube with Film

For bottom entry applications, stringent soldering control & pin alignment are required as lead to pad misalignment could cause incorrect mating.

By	LYH	CB	DR
DETAIL	DRAWING RELEASE	PACKING OPTIONS CHANGED	CHANGE TO SOLDER TEMP. INFORMATION
REV DATE	A 30/10/06	B 27/04/09	C 05/08/09



Tolerances (Except as noted)	Part Number:-	Date:-
Dimensions in mm	BG120	30 OCT 06
X: ± 0.30 X.X ± 0.20 X.XX ± 0.15 X.XXX ± 0.10	Description:-	
X: *±5° X: *±2° XX: *±1° XXX: *±0.5°	2.54mm PITCH SOCKET, DUAL ROW, SURFACE MOUNT, VERTICAL, DUAL ENTRY	
Third Angle Projection	THIS DRAWING IS CONFIDENTIAL AND MUST NOT BE COPIED OR DISCLOSED WITHOUT WRITTEN CONSENT	

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Scale NTS	Revision C	Material See Note	Drawn by LYH	Sheet No. E & OE 1/1